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(71) Applicant (for all designated States except US): 3M IN-NOVATIVE PROPERTIES COMPANY [US/US]; 3M Center, Post Office Box 33427, Saint Paul, MN 55133-3427 (US).

- (72) Inventor; and
- (75) Inventor/Applicant (for US only): KOYANAGI, Tatsunori [JP/JP]; 7-2-5, Hashimoto, Sagamihara-city, Kanagawa 229 (JP).
- (74) Agents: FONSECA, Darla P. et al.; Office of Intellectual Property Counsel, Post Office Box 33427, Saint Paul, MN 55133-3427 (US).
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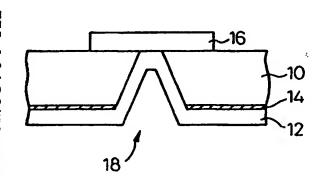
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(54) Title: MULTI-LAYER DOUBLE-SIDED WIRING BOARD AND METHOD OF FABRICATING THE SAME



(57) Abstract: The present invention provides a multi-layer double-sided wiring board which provides excellent adhesion between the conductive layer (12) and the insulating layer (10) because of the provision of an interface layer (14) therebetween, and which exhibits excellent conductivity reliability because the upper and lower conductive layers (16, 12) are joined together within the blind via (18) without interposing a dissimilar metal.